

## Analog-assisted digital low dropout regulator with fast transient response and low output ripple

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An analog-assisted digital low dropout regulator (AAD-LDO) is proposed to solve the problems of a slow transient response and a large output ripple in a conventional digital LDO. In the AAD-LDO, a fast-response auxiliary analog LDO is added to the digital LDO in parallel. Compared with the digital LDO, the measured AAD-LDO in 180 nm CMOS reduces the transient response time and the output ripple by 59 and 28%, respectively, at the same current efficiency of 97.1%. The line regulation is 15 mV/V and the load regulation is 0.63 mV/mA.

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### 1. Introduction

The number of on-chip voltage converters is increasing, because recent SoC's require a lot of power supply voltage. A low dropout regulator (LDO) is a reasonable choice for the on-chip voltage converters, because LDO requires no off-chip components. The low-power SoC's require a low-input-voltage LDO with the low quiescent current ( $I_Q$ ) (= supply current for a controller in LDO).<sup>1-23</sup> A digital LDO<sup>1-5,24,25</sup> achieves the low-input-voltage operation with a low  $I_Q$ . The problems of the digital LDO, however, are a slow transient response and a large output ripple. To solve these problems, an analog-assisted digital low dropout regulator (AAD-LDO) is proposed.

### 2. Problems of conventional LDOs

Figure 1 shows a conventional analog LDO. The current efficiency ( $\eta$ ) of the analog LDO is low owing to the high  $I_Q$  in the operational amplifier. Figure 2 shows a conventional digital LDO.<sup>1)</sup> In the digital LDO, the current efficiency is high owing to the low  $I_Q$  in the controller and the comparator, though the transient response is slow and the output ripple is large. In order to reduce the transient response time, a high-frequency clock (Clk) is required, which increases  $I_Q$  and decreases  $\eta$ .<sup>2,3)</sup> In order to reduce the ripple, the unit gate width ( $W_{UNIT}$ ) of the power transistors is reduced and the number ( $n$ ) of power transistors is increased. The increased  $n$ , however, increases  $I_Q$  and decreases  $\eta$ . Therefore, a new circuit is required to reduce both the transient response time and the ripple without decreasing  $\eta$ .

### 3. Proposed analog-assisted digital LDO

Figure 3 shows the concept of the proposed AAD-LDO. In the AAD-LDO, a fast-response auxiliary analog LDO is added to the digital LDO in parallel. Figure 4 shows a detailed schematic of the proposed AAD-LDO. In the AAD-LDO, the digital LDO is the main LDO and the analog LDO is auxiliary LDO, because  $W_{ANALOG} < W_{DIGITAL}$ . The digital LDO slowly controls the output voltage ( $V_{OUT}$ ) with a coarse digital voltage step. In contrast, the analog LDO quickly controls  $V_{OUT}$  with a fine analog voltage control. By operating both the digital LDO and the analog LDO simultaneously in parallel, the AAD-LDO reduces both the transient response time and the output ripple.

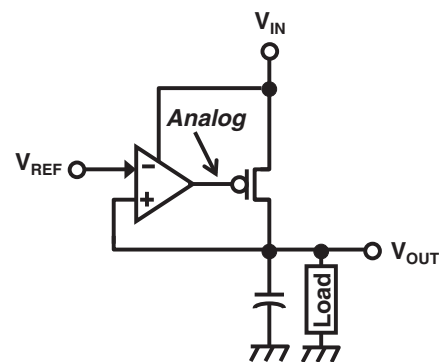


Fig. 1. Conventional analog LDO.

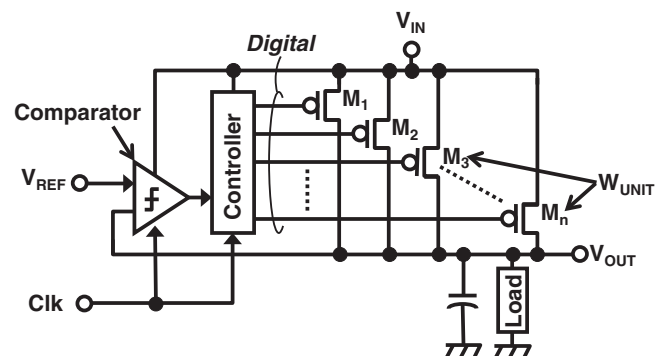


Fig. 2. Conventional digital LDO.<sup>1)</sup>

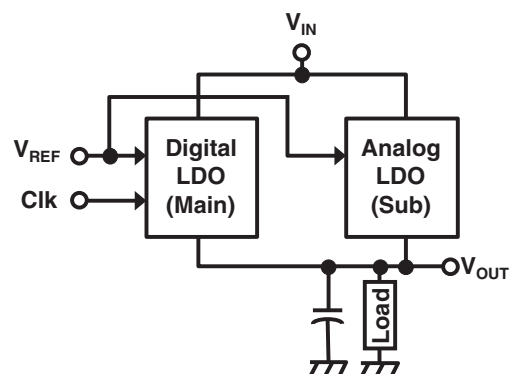


Fig. 3. Concept of proposed AAD-LDO.

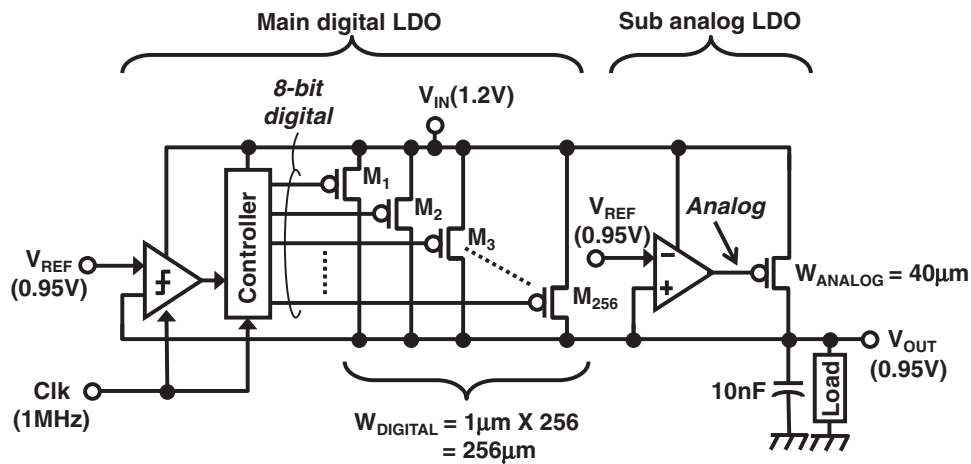


Fig. 4. Detailed schematic of proposed AAD-LDO.

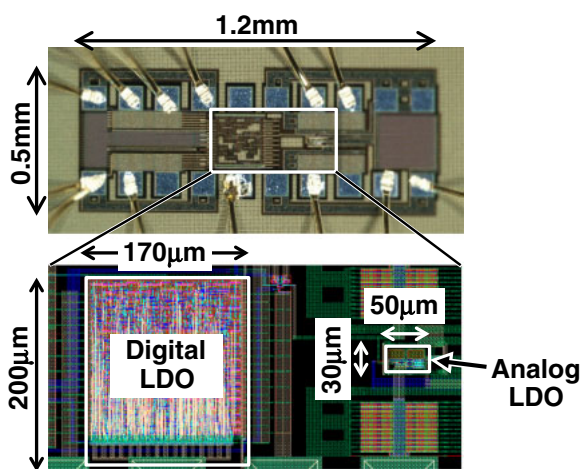


Fig. 5. (Color online) Chip photomicrograph and layout of AAD-LDO.

#### 4. Measurement results and discussion

Both the AAD-LDO and the digital LDO are fabricated in 180 nm CMOS. In the AAD-LDO and the digital LDO, the digital LDO part is the same and only the AAD-LDO has the analog LDO. Figure 5 shows the chip photomicrograph and the layout of the AAD-LDO. The total chip area was  $1.2 \times 0.5 \text{ mm}^2$ . The core areas of the digital and analog LDOs are  $200 \times 170 \mu\text{m}^2$  and  $30 \times 50 \mu\text{m}^2$ , respectively.

Table I shows a measured performance summary of the AAD-LDO. The fabricated AADLDO achieved the 1.2 V input voltage and 0.95 V output voltage with 99.6% current efficiency and a  $14.2 \mu\text{A}$  quiescent current at a 3.4 mA load current ( $I_{OUT}$ ). The static line regulation is 15 mV/V when the input voltage ( $V_{IN}$ ) is varied from 1.15 to 1.25 V. The static load regulation is 0.63 mV/mA when  $I_{OUT}$  is varied from 1.7 to 3.4 mA.

In the following measurement,  $V_{IN}$  is 1.2 V,  $V_{OUT}$  is 0.95 V, and  $I_{OUT}$  is 3.4 mA. The reference voltage ( $V_{REF}$ ) is changed from 0.8 to 0.95 V and the response time of  $V_{OUT}$  is measured at the load resistance of  $270 \Omega$ .

In the design of the LDO,  $\eta$ , the transient response time of  $V_{OUT}$ , and the ripple of  $V_{OUT}$  are three important characteristics. In the conventional digital LDO, the clock frequency is

Table I. Performance summary of AAD-LDO.

CMOS technology	180 nm
Active area	$0.036 \text{ mm}^2$
Clock frequency	1 MHz
Input voltage	1.2 V
Output voltage	0.95 V
Maximum load current	11 mA
Nominal load current ( $I_l$ )	3.4 mA
Output capacitor	10 nF (Off-chip)
Quiescent current at $I_l$	14.2–242 $\mu\text{A}$
Current efficiency at $I_l$	93.3–99.6%
Line regulation	15 mV/V
Load regulation	0.65 mV/mA

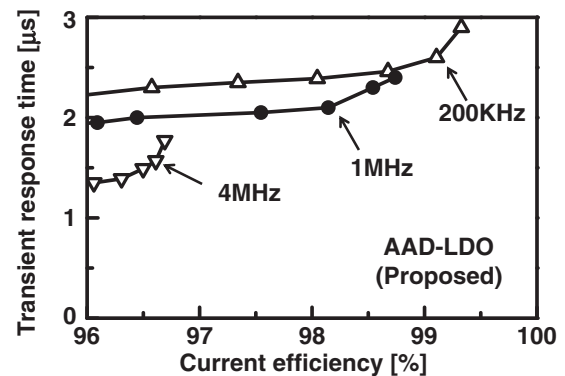


Fig. 6. Measured  $\eta$  dependence of transient response time in AAD-LDO.

a key parameter to tune the characteristics. In contrast, in the proposed AAD-LDO, both the clock frequency and the bias current of the operational amplifier in the analog LDO are key parameters to tune the characteristics.

In order to find the optimum clock frequency in the AAD-LDO, Fig. 6 shows the measured  $\eta$  dependence of the transient response time in the AAD-LDO. Both the clock frequency and the bias current are varied. When the clock frequency is increased from 200 kHz to 4 MHz, both the transient response time and  $\eta$  are reduced. In this work, the clock frequency of 1 MHz is used in the following measure-

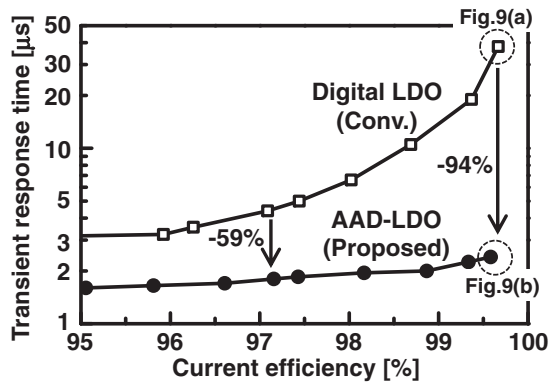


Fig. 7. Measured transient response time vs current efficiency.

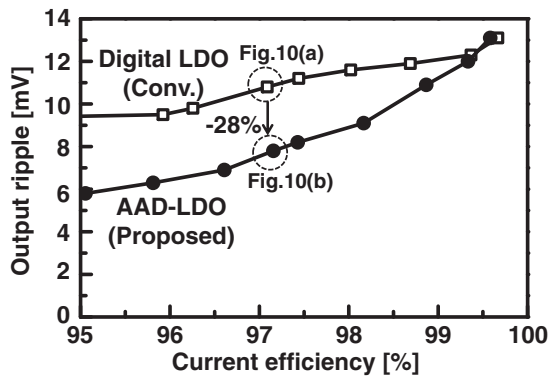


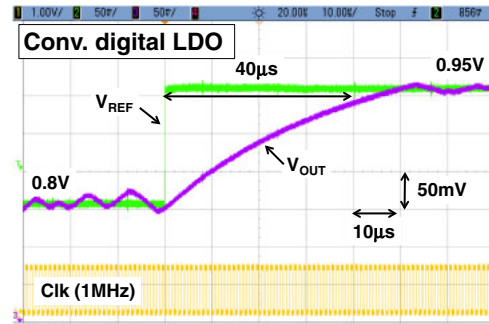
Fig. 8. Measured output ripple vs current efficiency.

ment to achieve  $\eta$  larger than 98% and a fast transient response time.

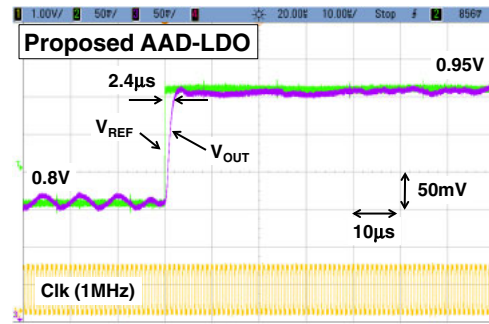
Figures 7 and 8 show the measured  $\eta$  dependence of the transient response time and the peak-to-peak ripple of  $V_{OUT}$ , respectively, in the conventional digital LDO and the proposed AAD-LDO. The clock frequency is varied from 1 to 14 MHz in the digital LDO, while the bias current of the operational amplifier is varied from 1 to 15  $\mu$ A in the AAD-LDO at the clock frequency of 1 MHz. Compared with the conventional digital LDO, the proposed AAD-LDO reduces the response time from 40 to 2.4  $\mu$ s by 94% and from 4.4 to 1.8  $\mu$ s by 59% at  $\eta$  of 99.6 and 97.1%, respectively. Figure 9 shows the measured waveforms of  $V_{REF}$  and  $V_{OUT}$  at  $\eta$  of 99.6%. Similarly, AAD-LDO reduces the ripple from 10.8 to 7.8 mV by 28% at  $\eta$  of 97.1%, as shown in Fig. 10.

In order to investigate the dynamic line regulation, Fig. 11 shows the measured waveforms of  $V_{IN}$  and  $V_{OUT}$  of the conventional digital LDO and the proposed AAD-LDO at  $\eta$  of 99.6%. The clock frequency is 1 MHz.  $V_{IN}$  is changed between 1.15 and 1.25 V at 10 kHz. In the digital LDO in Fig. 11(a), the transient drop of  $V_{OUT}$  at the falling edge of  $V_{IN}$  is 50 mV. In contrast, in AAD-LDO in Fig. 11(b), the transient drop is reduced to 5 mV by adding the fast-response auxiliary analog LDO.

In order to investigate the dynamic load regulation, Fig. 12 shows the measured waveforms of  $I_{OUT}$  and  $V_{OUT}$  of the conventional digital LDO and the proposed AAD-LDO at  $\eta$  of 97.1%. The clock frequencies of the digital LDO and AAD-LDO are 10 and 1 MHz, respectively.  $I_{OUT}$  is changed

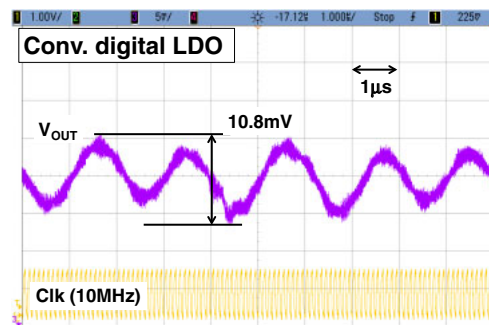


(a)

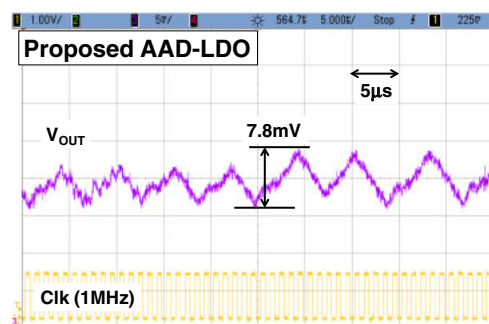


(b)

Fig. 9. (Color online) Measured transient waveforms of  $V_{REF}$  and  $V_{OUT}$  at  $\eta$  of 99.6%. (a) Conventional digital LDO. (b) Proposed AAD-LDO.



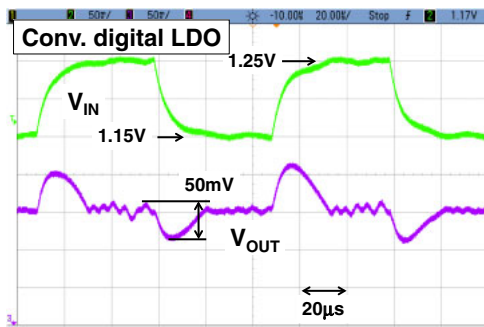
(a)



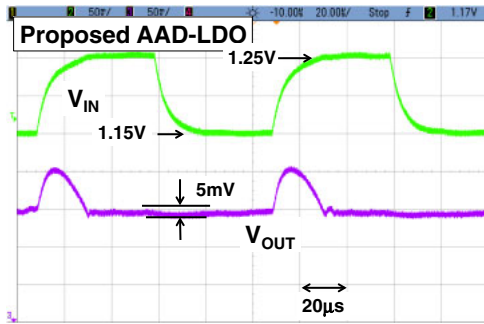
(b)

Fig. 10. (Color online) Measured output ripple waveforms at  $\eta$  of 97.1%. (a) Conventional digital LDO. (b) Proposed AAD-LDO.

between 1.7 and 3.4 mA at 10 kHz. In the digital LDO in Fig. 12(a), the transient drop of  $V_{OUT}$  is 100 mV. In contrast, in the AAD-LDO in Fig. 12(b), the transient drop is reduced to 40 mV by adding the fast-response auxiliary analog LDO.

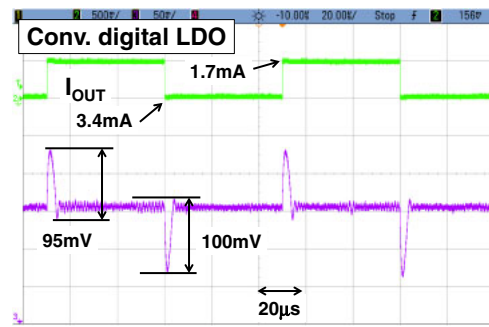


(a)

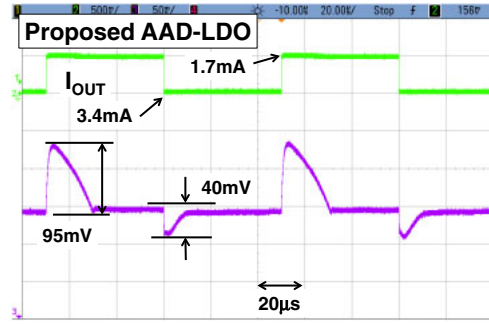


(b)

**Fig. 11.** (Color online) Measured waveforms of  $V_{IN}$  and  $V_{OUT}$ . (a) Conventional digital LDO. (b) Proposed AAD-LDO.



(a)



(b)

**Fig. 12.** (Color online) Measured waveforms of  $I_{OUT}$  and  $V_{OUT}$ . (a) Conventional digital LDO. (b) Proposed AAD-LDO.

**5. Conclusions**

The AAD-LDO is proposed to solve the problems of the slow transient response and the large output ripple in a conventional digital LDO. Compared with the digital LDO, the measured AAD-LDO in 180 nm CMOS reduces the transient response time and the output ripple by 59 and 28%, respectively, at the same current efficiency of 97.1%. At the dynamic change of  $V_{IN}$ , the transient drop of  $V_{OUT}$  is reduced from 50 to 5 mV by adding the fast-response auxiliary analog LDO in the AAD-LDO. Similarly, at the dynamic change of  $I_{OUT}$ , the transient drop of  $V_{OUT}$  is reduced from 100 to 40 mV in the AAD-LDO.

**Acknowledgements**

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